

Antec
Believe it.

FORMULA 6 NANO DIAMOND THERMAL COMPOUND

ACCESSORIES



Antec's Formula 6 thermal compound protects your CPU even when your rig is running on all cylinders. Since little of the CPU's surface actually touches the heat sink, you need a solution that isolates and facilitates the transfer of heat. Formula 6's nano diamond particles minimize the distance between heat-conductive compounds and gladly take on the highest demanding CPU, optimally performing between -30°C and 250°C. To keep your system cool and your CPU functioning comfortably, pick up Antec's Formula 6 for a diamond-caliber solution.

SPECIAL FEATURES:

- Diamond particles measuring 0.0000015 cm rated at 5.3 w/mK
- Extended -30°C to 250°C stable temperature range ideal for performance cooling
- Lighter, easier to spread stable composition won't crack or dry out
- Quantity: 4 g
- Specific gravity: 2.2 g / cm³

UPC# 0-761345-77060-6

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